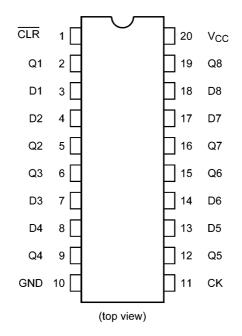
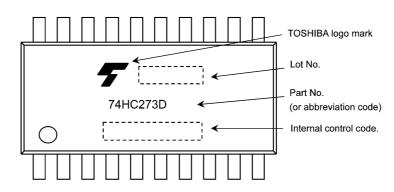
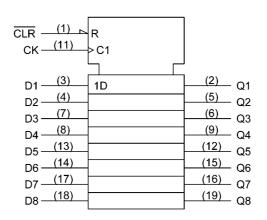
# 5. Pin Assignment



# 6. Marking



7. IEC Logic Symbol

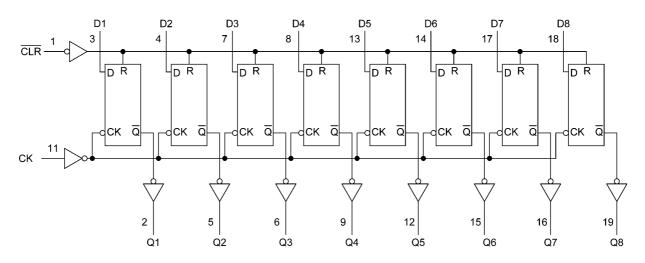


# 8. Truth Table

	Inputs		Output	Function
	D	СК	Q	Function
L	Х	Х	L	Clear
н	L		L	—
н	Н		Н	—
н	X		Qn	No Change

X: Don't care

# 9. System Diagram



# 10. Absolute Maximum Ratings (Note)

Characteristics	Symbol	Note	Rating	Unit
Supply voltage	V <sub>CC</sub>		-0.5 to 7.0	V
Input voltage	V <sub>IN</sub>		-0.5 to V <sub>CC</sub> + 0.5	V
Output voltage	V <sub>OUT</sub>		-0.5 to V <sub>CC</sub> + 0.5	V
Input diode current	I <sub>IK</sub>		±20	mA
Output diode current	I <sub>ОК</sub>		±20	mA
Output current	I <sub>OUT</sub>		±25	mA
V <sub>CC</sub> /ground current	I <sub>CC</sub>		±50	mA
Power dissipation	PD	(Note 1)	500	mW
Storage temperature	T <sub>stg</sub>		-65 to 150	°C

Note: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: P<sub>D</sub> derates linearly with -8 mW/°C above 85°C

## 11. Operating Ranges (Note)

Characteristics	Symbol	Test Condition	Rating	Unit
Supply voltage	V <sub>CC</sub>	—	2.0 to 6.0	V
Input voltage	V <sub>IN</sub>	—	0 to V <sub>CC</sub>	V
Output voltage	V <sub>OUT</sub>	—	0 to V <sub>CC</sub>	V
Operating temperature	T <sub>opr</sub>	—	-40 to 125	°C
Input rise and fall times	t <sub>r</sub> ,t <sub>f</sub>	_	0 to 50	μS

Note: The operating ranges must be maintained to ensure the normal operation of the device. Unused inputs and bus inputs must be tied to either  $V_{CC}$  or GND.

# 12. Electrical Characteristics

# 12.1. DC Characteristics (Unless otherwise specified, $T_a = 25 \text{ °C}$ )

Characteristics	Symbol	Test Condition	n	V <sub>CC</sub> (V)	Min	Тур.	Max	Unit
High-level input voltage	VIH	—		2.0	1.50	_	_	V
				4.5	3.15	_	_	
				6.0	4.20	_	_	
Low-level input voltage	VIL	_		2.0	_	_	0.50	V
				4.5	_	—	1.35	
				6.0	_	—	1.80	
High-level output voltage	V <sub>OH</sub>	$V_{IN} = V_{IH} \text{ or } V_{IL}$	I <sub>OH</sub> = -20 μA	2.0	1.9	2.0	_	V
				4.5	4.4	4.5	—	
				6.0	5.9	6.0	_	
			I <sub>OH</sub> = -4 mA	4.5	4.18	4.31	_	
			I <sub>OH</sub> = -5.2 mA	6.0	5.68	5.80	—	
Low-level output voltage	V <sub>OL</sub>	$V_{IN} = V_{IH} \text{ or } V_{IL}$	I <sub>OL</sub> = 20 μA	2.0	_	0.0	0.1	V
				4.5		0.0	0.1	
				6.0	_	0.0	0.1	
			I <sub>OL</sub> = 4 mA	4.5	_	0.17	0.26	
			I <sub>OL</sub> = 5.2 mA	6.0	_	0.18	0.26	
Input leakage current	I <sub>IN</sub>	$V_{IN} = V_{CC}$ or GND	)	6.0	_	_	±0.1	μA
Quiescent supply current	I <sub>CC</sub>	$V_{IN} = V_{CC}$ or GND	)	6.0	_	_	4.0	μA

# 12.2. DC Characteristics (Unless otherwise specified, $T_a = -40$ to 85 °C)

Characteristics	Symbol	Test Conditior	ı	V <sub>CC</sub> (V)	Min	Max	Unit
High-level input voltage	V <sub>IH</sub>	_		2.0	1.50	_	V
				4.5	3.15	_	
				6.0	4.20	_	
Low-level input voltage	V <sub>IL</sub>	—		2.0	_	0.50	V
				4.5	_	1.35	
				6.0		1.80	
High-level output voltage	V <sub>OH</sub>	$V_{IN} = V_{IH} \text{ or } V_{IL}$	I <sub>OH</sub> = -20 μA	2.0	1.9	_	V
				4.5	4.4	_	
				6.0	5.9	_	
			I <sub>OH</sub> = -4 mA	4.5	4.13	_	
			I <sub>OH</sub> = -5.2 mA	6.0	5.63	_	
Low-level output voltage	V <sub>OL</sub>	$V_{IN} = V_{IH} \text{ or } V_{IL}$	I <sub>OL</sub> = 20 μA	2.0		0.1	V
				4.5	_	0.1	1
				6.0	_	0.1	
			I <sub>OL</sub> = 4 mA	4.5	_	0.33	
			I <sub>OL</sub> = 5.2 mA	6.0	_	0.33	
Input leakage current	l <sub>iN</sub>	$V_{IN} = V_{CC}$ or GND		6.0	_	±1.0	μA
Quiescent supply current	I <sub>CC</sub>	$V_{IN} = V_{CC}$ or GND		6.0		40.0	μA

# 12.3. DC Characteristics (Unless otherwise specified, $T_a = -40$ to 125 °C)

Characteristics	Symbol	Test Conditior	ı	V <sub>CC</sub> (V)	Min	Max	Unit
High-level input voltage	V <sub>IH</sub>	—		2.0	1.50	—	V
				4.5	3.15	_	
				6.0	4.20	_	]
Low-level input voltage	VIL	—		2.0	_	0.50	V
				4.5		1.35	
				6.0	_	1.80	
High-level output voltage	V <sub>OH</sub>	$V_{IN} = V_{IH} \text{ or } V_{IL}$	I <sub>OH</sub> = -20 μA	2.0	1.9	_	V
				4.5	4.4	_	
				6.0	5.9	_	
			I <sub>OH</sub> = -4 mA	4.5	3.7	_	
			I <sub>OH</sub> = -5.2 mA	6.0	5.2	_	
Low-level output voltage	V <sub>OL</sub>	$V_{IN} = V_{IH} \text{ or } V_{IL}$	I <sub>OL</sub> = 20 μA	2.0	_	0.1	V
				4.5	_	0.1	
				6.0		0.1	
			I <sub>OL</sub> = 4 mA	4.5	_	0.4	
			I <sub>OL</sub> = 5.2 mA	6.0	_	0.4	]
Input leakage current	I <sub>IN</sub>	$V_{IN} = V_{CC}$ or GND		6.0	_	±1.0	μA
Quiescent supply current	I <sub>CC</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND		6.0	_	160.0	μA

# 12.4. Timing Requirements (Unless otherwise specified, $T_a = 25^{\circ}C$ , Input: $t_r = t_f = 6$ ns)

Characteristics	Symbol	Test Condition	V <sub>CC</sub> (V)	Limit	Unit
Minimum pulse width	t <sub>w(L)</sub> ,t <sub>w(H)</sub>	_	2.0	75	ns
(CK)			4.5	15	]
			6.0	13	
Minimum pulse width	t <sub>w(L)</sub>	_	2.0	75	ns
(CLR)			4.5	15	
			6.0	13	
Minimum setup time	t <sub>S</sub>	_	2.0	75	ns
			4.5	15	
			6.0	13	
Minimum hold time	t <sub>h</sub>	—	2.0	0	ns
			4.5	0	
			6.0	15 13 0	
Minimum removal time	t <sub>rem</sub>	—	2.0	50	ns
(CLR)			4.5	10	
			6.0	9	]
Clock frequency	f	_	2.0	6	MHz
			4.5	30	
			6.0	35	

12.5. Timing Requirements (Unless otherwise specified,  $T_a$  = -40 to 85°C, Input:  $t_r$  =  $t_f$  = 6 ns)

Characteristics	Symbol	Test Condition	V <sub>CC</sub> (V)	Limit	Unit
Minimum pulse width	t <sub>w(L)</sub> ,t <sub>w(H)</sub>	—	2.0	95	ns
(CK)			4.5	19	
			6.0	16	
Minimum pulse width	t <sub>w(L)</sub>	_	2.0	95	ns
(CLR)			4.5	19	
			6.0	16	
Minimum setup time	ts	_	2.0	95	ns
			4.5	19	
			6.0	16	
Minimum hold time	t <sub>h</sub>	_	2.0	0	ns
			4.5	0	
			6.0	0	
Minimum removal time	t <sub>rem</sub>	_	2.0	65	ns
(CLR)			4.5	13	
			6.0	11	
Clock frequency	f	_	2.0	5	MHz
			4.5	24	
			6.0	28	

### 12.6. Timing Requirements (Unless otherwise specified, T<sub>a</sub> = -40 to 125 °C, Input: t<sub>r</sub> = t<sub>f</sub> = 6 ns)

Characteristics	Symbol	Test Condition	V <sub>CC</sub> (V)	Limit	Unit
Minimum pulse width	t <sub>w(L)</sub> ,t <sub>w(H)</sub>	_	2.0	120	ns
(CK)			4.5	24	
			6.0	20	
Minimum pulse width	t <sub>w(L)</sub>	_	2.0	120	ns
(CLR)			4.5	24	
			6.0	20	
Minimum setup time	ts	_	2.0	120	ns
			4.5	24	
			6.0	20	
Minimum hold time	t <sub>h</sub>	_	2.0	0	ns
			4.5	0	
			6.0	0	1
Minimum removal time	t <sub>rem</sub>	_	2.0	75	ns
(CLR)			4.5	15	
			6.0	13	
Clock frequency	f	_	2.0	4	MHz
			4.5	20	1
			6.0	24	]

#### 12.7. AC Characteristics (Unless otherwise specified, C<sub>L</sub> = 15 pF, V<sub>CC</sub> = 5 V, T<sub>a</sub> = 25 °C, Input: t<sub>r</sub> = t<sub>f</sub> = 6 ns)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Output transition time	t <sub>TLH</sub> ,t <sub>THL</sub>	—	_	4	8	ns
Propagation delay time (CK-Q)	t <sub>PLH</sub> ,t <sub>PHL</sub>	_	_	15	25	ns
Propagation delay time (CLR-Q)	t <sub>PHL</sub>	—	—	16	27	ns
Maximum clock frequency	f <sub>MAX</sub>	_	40	67	_	MHz

### 12.8. AC Characteristics (Unless otherwise specified, $C_L = 50 \text{ pF}$ , $T_a = 25 \text{ }^\circ\text{C}$ , Input: $t_r = t_f = 6 \text{ ns}$ )

Characteristics	Symbol	Note	Test Condition	V <sub>CC</sub> (V)	Min	Тур.	Max	Unit
Output transition time	t <sub>TLH</sub> ,t <sub>THL</sub>		_	2.0	_	25	75	ns
				4.5	_	7	15	
				6.0	_	6	13	
Propagation delay time	t <sub>PLH</sub> ,t <sub>PHL</sub>		_	2.0	_	54	145	ns
(CK-Q)				4.5	_	18	29	
				6.0	_	15	25	
Propagation delay time	t <sub>PHL</sub>		_	2.0	_	60	160	ns
(CLR-Q)				4.5	_	20	32	
				6.0	_	17	27	
Maximum clock frequency	f <sub>MAX</sub>		_	2.0	6	18	_	MHz
				4.5	30	56	_	
				6.0	36	66	_	
Input capacitance	C <sub>IN</sub>		_	_	_	3		pF
Power dissipation capacitance	C <sub>PD</sub>	(Note 1)	_	_	_	11	_	pF

Note 1: C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation.

 $I_{CC(opr)} = C_{PD} \times V_{CC} \times f_{IN} + I_{CC}/8$  (per bit)

# 12.9. AC Characteristics

# (Unless otherwise specified, $C_L$ = 50 pF, $T_a$ = -40 to 85 °C, Input: $t_r$ = $t_f$ = 6 ns)

Characteristics	Symbol	Test Condition	V <sub>CC</sub> (V)	Min	Max	Unit
Output transition time	t <sub>TLH</sub> ,t <sub>THL</sub>	_	2.0	_	95	ns
			4.5	_	19	
			6.0	—	16	
Propagation delay time	t <sub>PLH</sub> ,t <sub>PHL</sub>	_	2.0	_	180	ns
(CK-Q)			4.5	_	36	
			6.0	_	31	
Propagation delay time	t <sub>PHL</sub>	_	2.0	_	200	ns
(CLR-Q)			4.5	_	40	
			6.0	_	34	]
Maximum clock frequency	f <sub>MAX</sub>	_	2.0	5	_	MHz
			4.5	24	_	
			6.0	28	_	]

## 12.10. AC Characteristics (Unless otherwise specified, $C_L = 50 \text{ pF}$ , $T_a = -40$ to 125 °C, Input: $t_r = t_f = 6 \text{ ns}$ )

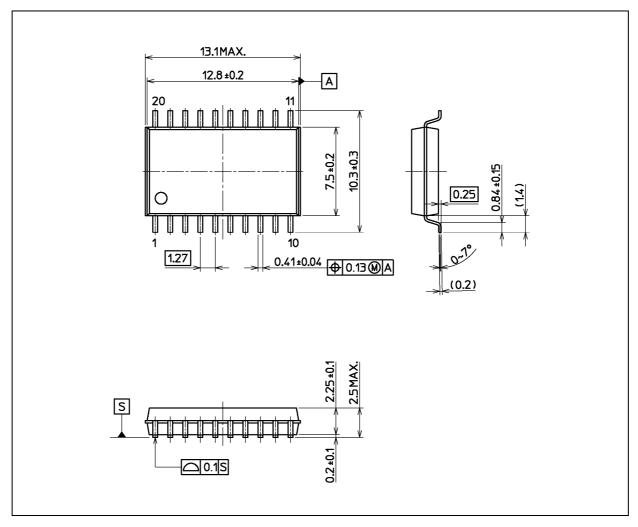
Characteristics	Symbol	Test Condition	V <sub>CC</sub> (V)	Min	Max	Unit
Output transition time	t <sub>TLH</sub> ,t <sub>THL</sub>	_	2.0	_	110	ns
			4.5	_	22	
			6.0	_	19	
Propagation delay time (CK-Q)	t <sub>PLH</sub> ,t <sub>PHL</sub>	_	2.0	_	225	ns
			4.5	_	45	
			6.0	_	38	
Propagation delay time (CLR-Q)	t <sub>PHL</sub>	_	2.0	_	225	ns
			4.5	_	45	
			6.0	_	38	
Maximum clock frequency	f <sub>MAX</sub>	—	2.0	4	_	MHz
			4.5	20	_	
			6.0	24	_	



# **Package Dimensions**

74HC273D

Unit: mm



Weight: 0.51 g (typ.)

Package Name(s)

Nickname: SOIC20

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